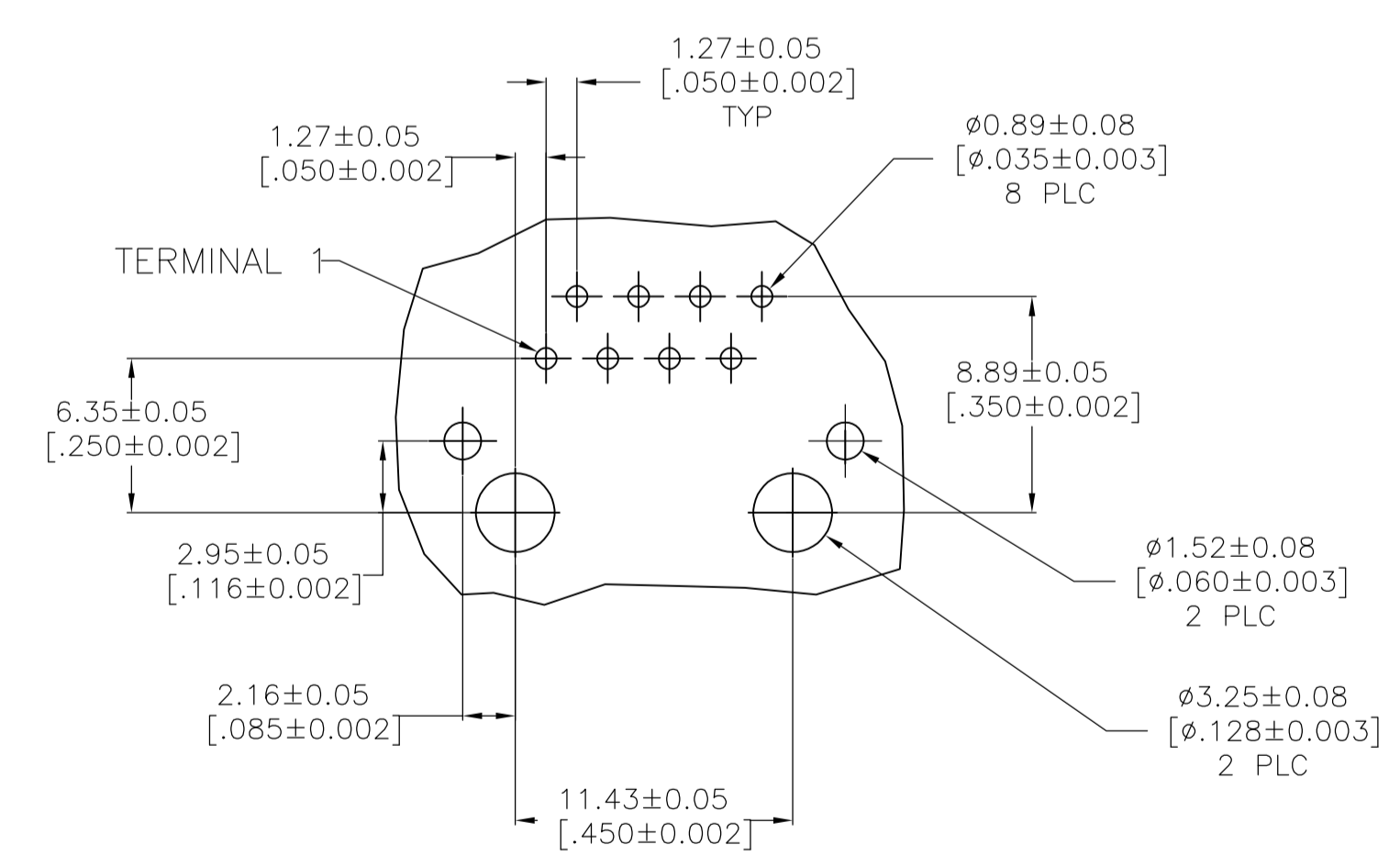
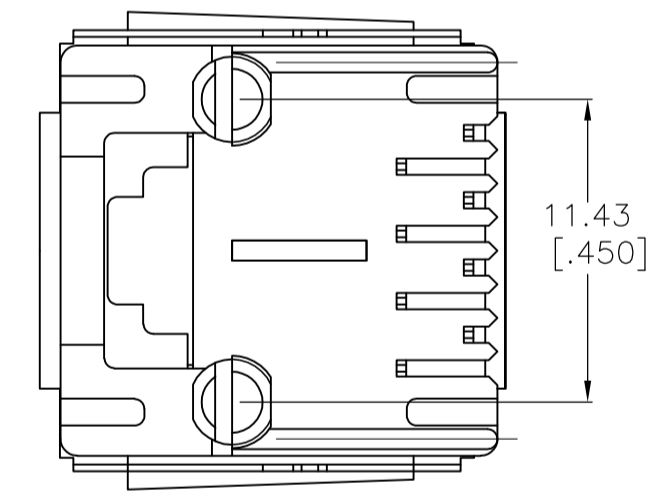
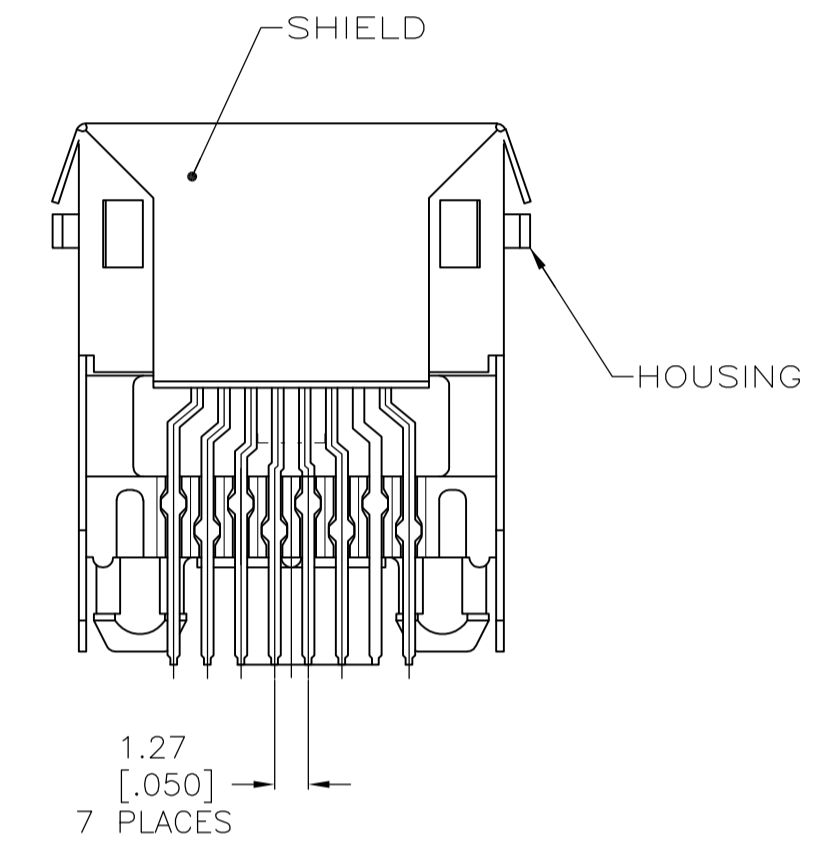
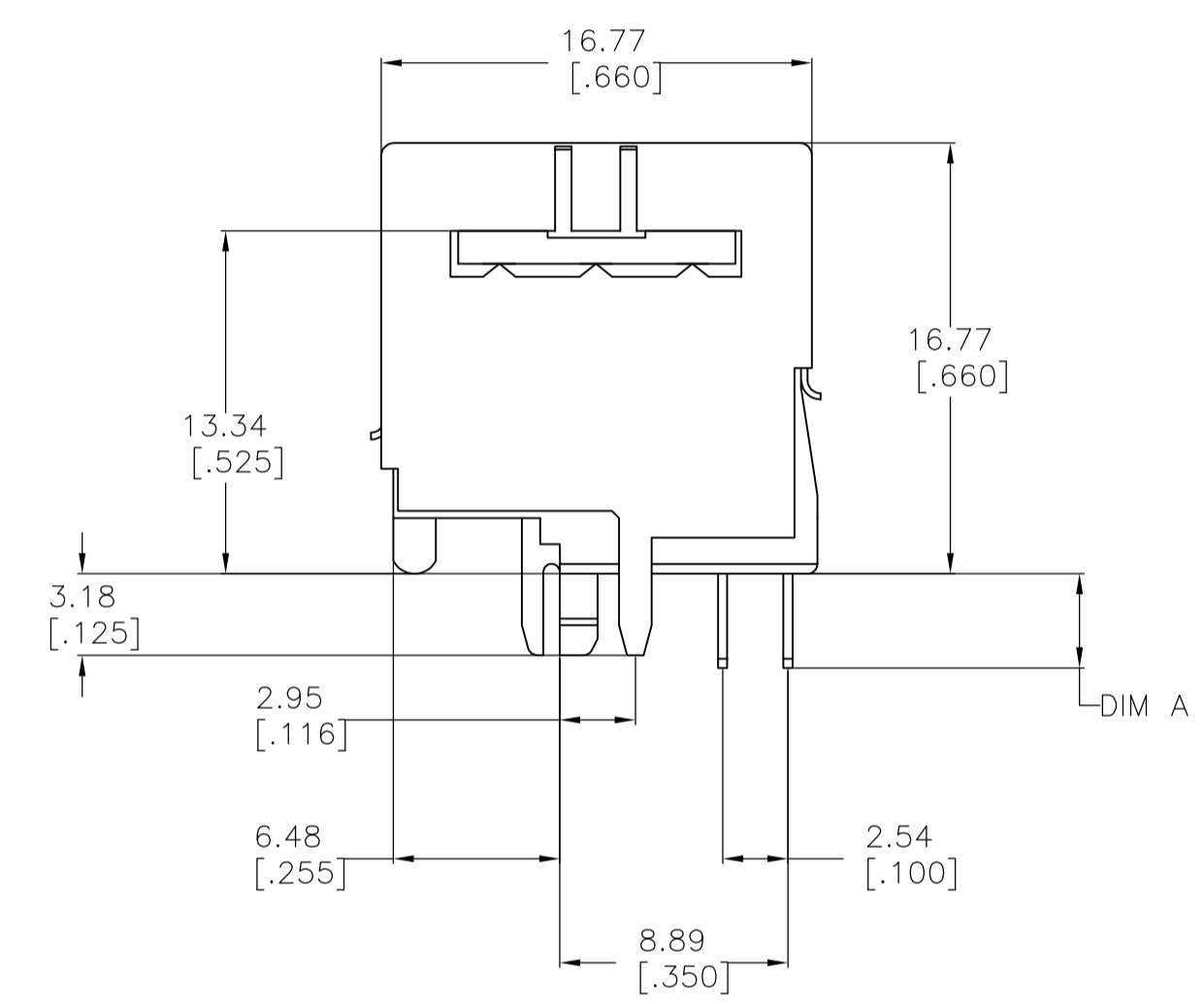
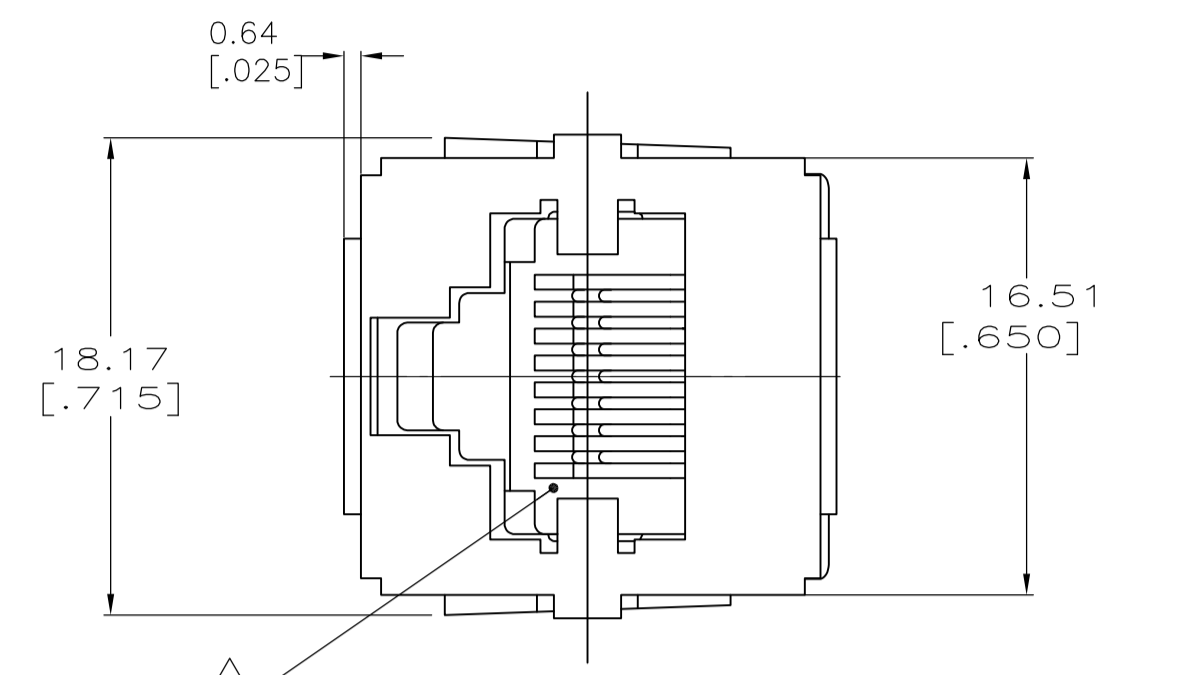
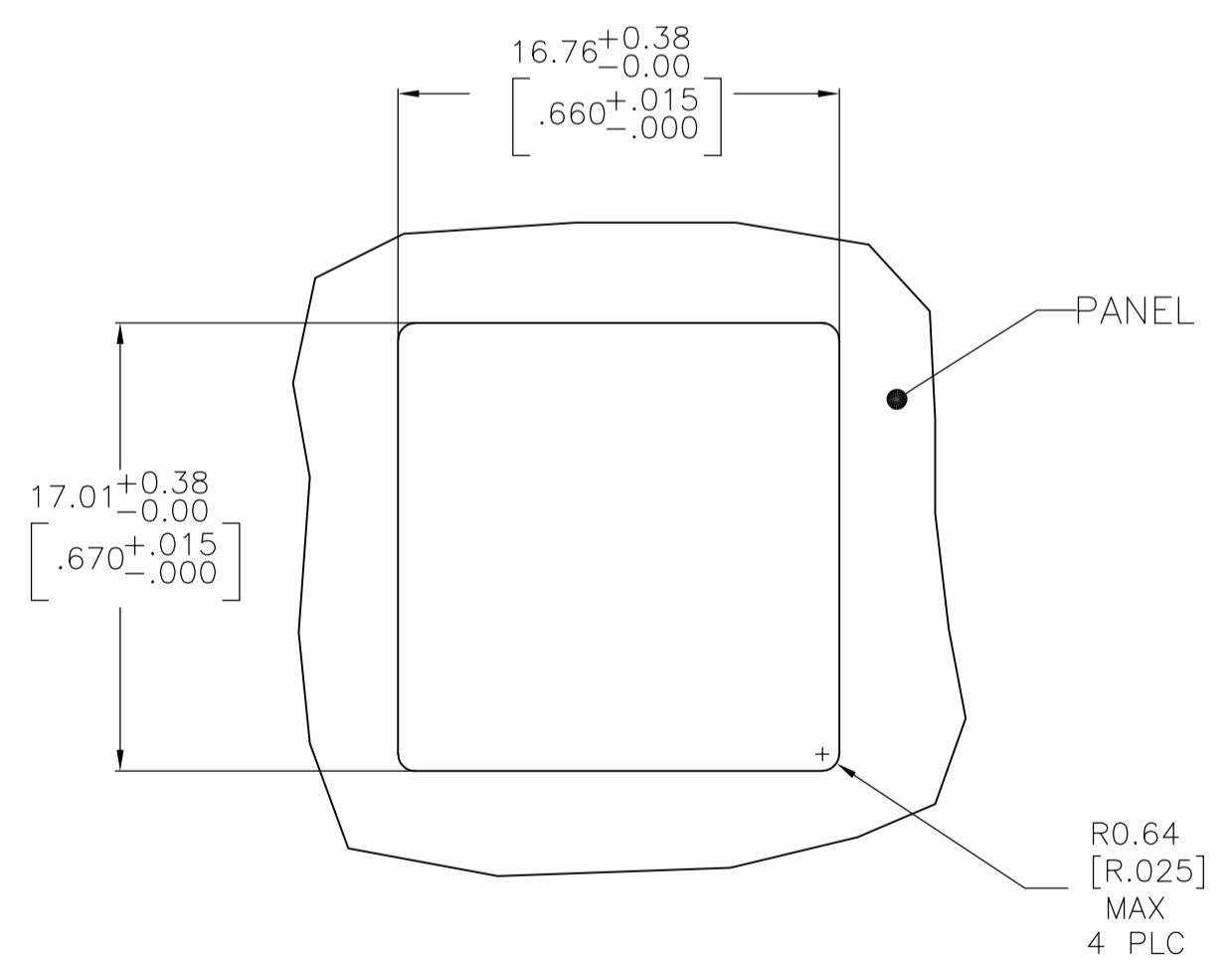


REVISIONS					
P	LTR	DESCRIPTION	DATE	DMN	APVD
E	REVISED PER ECO-17-000241		09JAN2017	AD	SH



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT COMPONENT SIDE SHOWN



RECOMMENDED PANEL CUTOUT

1

MATERIAL:
HOUSING – POLYESTER MOLDING COMPOUND, COLOR: BLACK
TERMINALS – 0.35[.0138] THICK PHOS BRONZE PLATED WITH 1.27µm[.000050] MIN THICK GOLD IN LOCALIZED AREA AND 3.81µm[.000150] MIN THICK MATTE TIN IN SOLDER AREA OVER 1.27µm[.000050] MIN THICK NICKEL UNDERPLATE
SHIELD – COPPER ZINC ALLOY PLATED WITH 3.0µm [.000120] MIN THICK REFLOWED TIN.

2

CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68 AND REA BULLETIN 345-81, PE-76 SPECIFICATION FOR MODULAR TELEPHONE HARDWARE.

3

MATERIAL:
HOUSING – HIGH TEMP THERMOPLASTIC-LCP, COLOR: BLACK
TERMINALS – 0.35[.0138] THICK PHOS BRONZE PLATED WITH 1.27µm[.000050] MIN THICK GOLD IN LOCALIZED AREA AND 3.81µm[.000150] MIN THICK MATTE TIN IN SOLDER AREA OVER 1.27µm[.000050] MIN THICK NICKEL UNDERPLATE
SHIELD – COPPER ZINC ALLOY PLATED WITH 3.0µm [.000120] MIN THICK REFLOWED TIN.

4

RECOMMENDED DIAMETER OF POSITION HOLE ON PCB FOR 5557969-3 IS 3.175±0.08MM

4	3	2.79-3.56 [.125±.015]	5557969-3
	1	2.79-3.30 [.120±.010]	5557969-2
	1	2.79-3.56 [.125±.015]	5557969-1
MATERIAL		DIM A	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DIN A. FERNANDEZ-DOCKS 08JUN2005		TE Connectivity	
DIMENSIONS: mm [INCHES]		TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD S. FLICKINGER 08JUN2005	
0 PLC ± -		1 PLC ± -		PRODUCT SPEC 108-1163	
1 PLC ± -		2 PLC ± 0.13[.005]		APPLICATION SPEC 114-2048	
2 PLC ± -		3 PLC ± -		SIZE CASE CODE DRAWING NO	
3 PLC ± -		4 PLC ± -		WEIGHT 0.000000A1 00779 5557969	
ANGLES ± -		FINISH SEE NOTE 1		CUSTOMER DRAWING SCALE 4:1 SHEET 1 OF 1 REV E	